

ABSTRACT

Disclosed is an adhesive composition containing a thermosetting resin, a curing agent, an elastomer, and an inorganic filler, in which the curing agent includes a phenolic resin having an alicyclic ring, and the content of the elastomer is 10 to 80 parts by mass with respect to 100 parts by mass of the thermosetting resin. Furthermore, a film-form adhesive that uses such an adhesive composition is disclosed. Moreover, an adhesive sheet that uses such a film-form adhesive, and a method for producing a semiconductor device are disclosed.

No Suitable Figure